

承認書

APPROVAL SHEETS

客戶名稱 : 鴻海精密工業股份有限公司
MESSRS

品名 : DC POWER JACK
DESCRIPTION

料號 : SHD-5014SGLH6-ES-L2-TR
PART NO

客戶料號
CUSTOMER :
PART NO

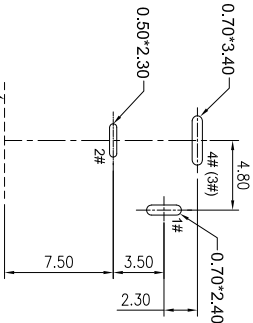
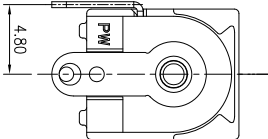
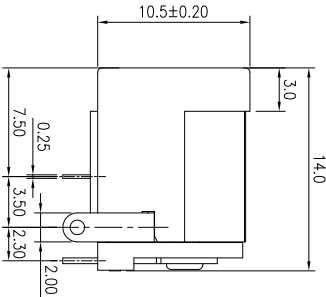
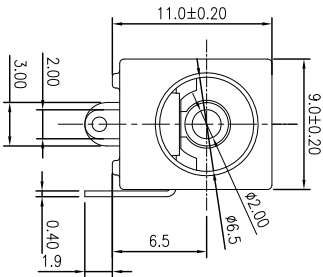
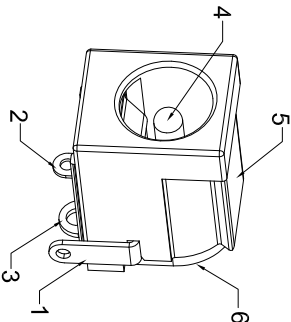
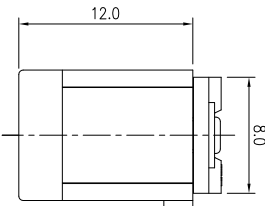
承認印 APPROVED BY



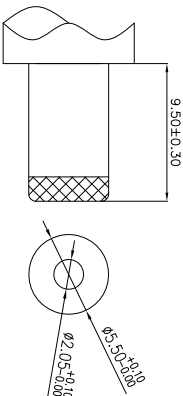
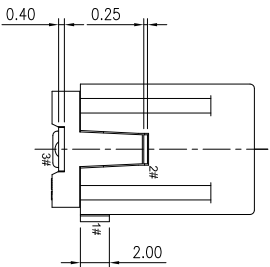
博 歲 電 子 股 份 有 限 公 司
POWERWAY ELECTRONICS CO., LTD.
佳 俊 有 限 公 司
BEST SMART LIMITED
2 4 1 6 1 新北市三重區中華路 18 號 3 樓
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District, New Taipei City 24161, Taiwan
TEL : 886-2-2986-6161 FAX : 886-2-2971-8665

SHD-5014SGLH6-ES-L2-TR

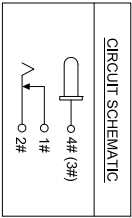
Series
Type
Terminal Plated
E: Silver-Plated
Housing Material
L2: LCP
Terminal Material
S: SUS



PCB EDGE
RECOMMENDED PCB LAYOUT
TOP VIEW
TOLERANCE: ±0.05mm
PCB THICKNESS: 1.00±0.05mm



PLUG DIAGRAM (TOL:±0.05)



6	Housing Cover	Nylon	
5	Housing	LCP	
4	Center Pin	Brass	Nickel-Plated(50u" Min.)
3	Center Pin Terminal	Brass	Silver-Plated(20u" Min.)
2	Tip Spring	SUS	Silver-Plated(20u" Min.)
1	Shunt Terminal	Brass	Silver-Plated(20u" Min.)

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POWERWAY ELECTRONICS CO.,LTD.

FILE NO.	SHD-5014GL (SERIES)	TITLE	DC POWER JACK
PART NO.	SHD-5014SGLH6-ES-L2-TR	DESIGNED BY	Etc 2019/03/25

TOLERANCE(公差):
0.000 mm ± 0.075 mm
0.00 mm ± 0.15 mm
0.0 mm ± 0.25 mm

UNIT	mm	REV.	A.0	CHECKED BY	Aaron 2019/03/25
SCALE	1:1	SHEET	1/1	APPROVED BY	

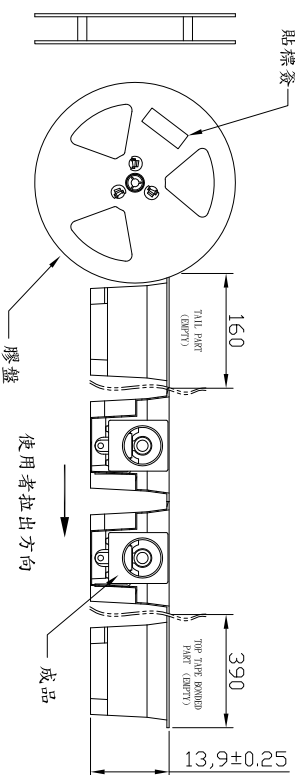
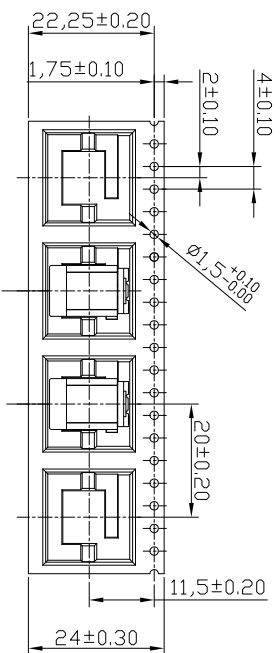
ZONE REV. DESCRIPTION DATE CHANGE

1 2 3 4 5 6 7 8

1. 包材:

卷料式包裝帶 1 SET
流程單編號標籤 1 PC
無鉛製程標籤 1 PC
1*210=210 PCS
PS TAPE REEL 1 SET
1*210=210 PCS

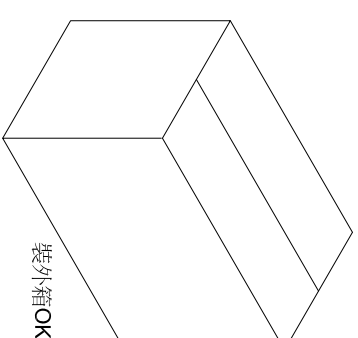
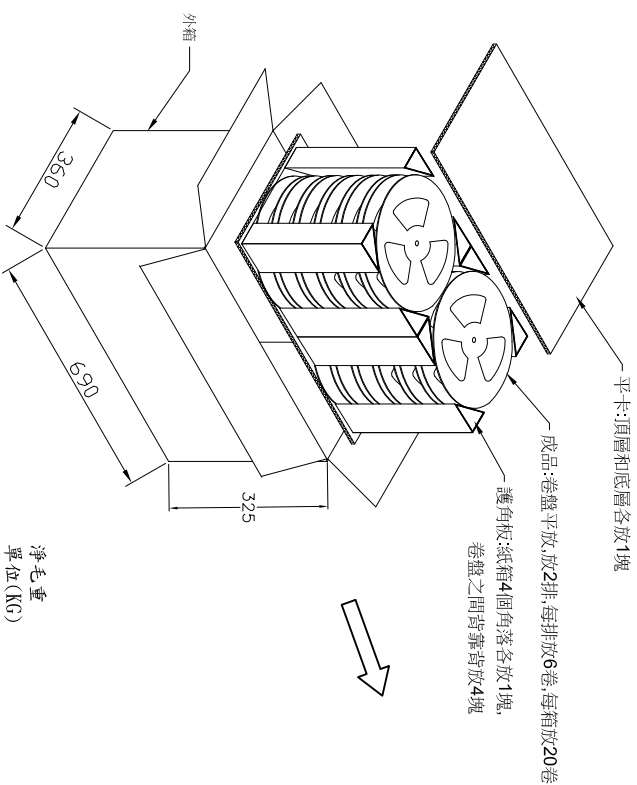
數量:
PACKING MATERIAL:
Q' TY:



2. 包材:

外箱 1 PC
無鉛製程標籤 1PC
平卡/紙板 2PC
210*20=4200 PCS
CARTON 1 PC
210*20=4200 PCS

數量:
PACKING MATERIAL:
Q' TY:



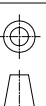
淨毛重
單位(KG)
數量
單位(PCS)

P / N	N.W.	G.W.	Q'TY
SHD-5014SGLH6-ES-L2-TR	**Kg	**±0.3Kg	4200

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TOLERANCE(公差):

0,000 mm ±
0,00 mm ±
0,0 mm ±



UNIT
單位
SCALE
比例

mm
inch
1:1

REV.
版本
SHEET
頁次

A.0
1/1

CHECKED
BY
APPROVED
BY

Eric
2019-03-26
Aaron
2019-03-26



DC POWER JACK SPECIFICATION FOR REFLOW SOLDERING PROCESS

1. Materials and Finish:

1.1 Housing

- ◆ Thermoplastic
- ◆ Color: Black or Optional Color Available on Demand

1.2 Contact

- ◆ Alloy: (See Material Specifications for Reference)
- ◆ Contact Area: Optional Tin, Silver, Gold Flash or Nickel plating
- ◆ Solder Area: Tin Plating or Nickel Plating
- ◆ Under-Plating: Nickel over all

1.3 Center Pin

- ◆ Alloy: (See Material Specifications for Reference)
- ◆ Nickel Plating

1.4 Shell(option)

- ◆ Alloy (See Material Specifications for Reference)
- ◆ Nickel plating

※ Expiration For Plating: 6 months storage period under non-unpacked parts (40%~60%RH)

2. Rating:

- ◆ Current & Voltage:

Diameter of Center Pin(mm)	Rated voltage (V)	Rated current(A)
Less than or equal 1.30mm	12	1
1.65mm		2
greater than or equal 2.00mm		3

- ◆ Storage & Operating Temperature: -25°C~70°C

**3. Electrical Performance:**

Item		Test conditions	Performance
3.1	Contact Resistance	EIA-364-23B. Subject specimens to 100 mA maximum and 20 mV maximum dry circuit voltage	50mΩ Max (initial)
3.2	Insulation Resistance	EIA-364-21C. Subject specimens to DC 500V and measure insulation resistance between adjacent contacts, also measure between the contacts and the shield.	100MΩ Min.
3.3	Dielectric Withstanding Voltage	EIA-364-20B. Subject specimens to 500VAC (50—60Hz) for 1 minute between terminals and ground.	No discharge or breakdown

4. Mechanical Performance:

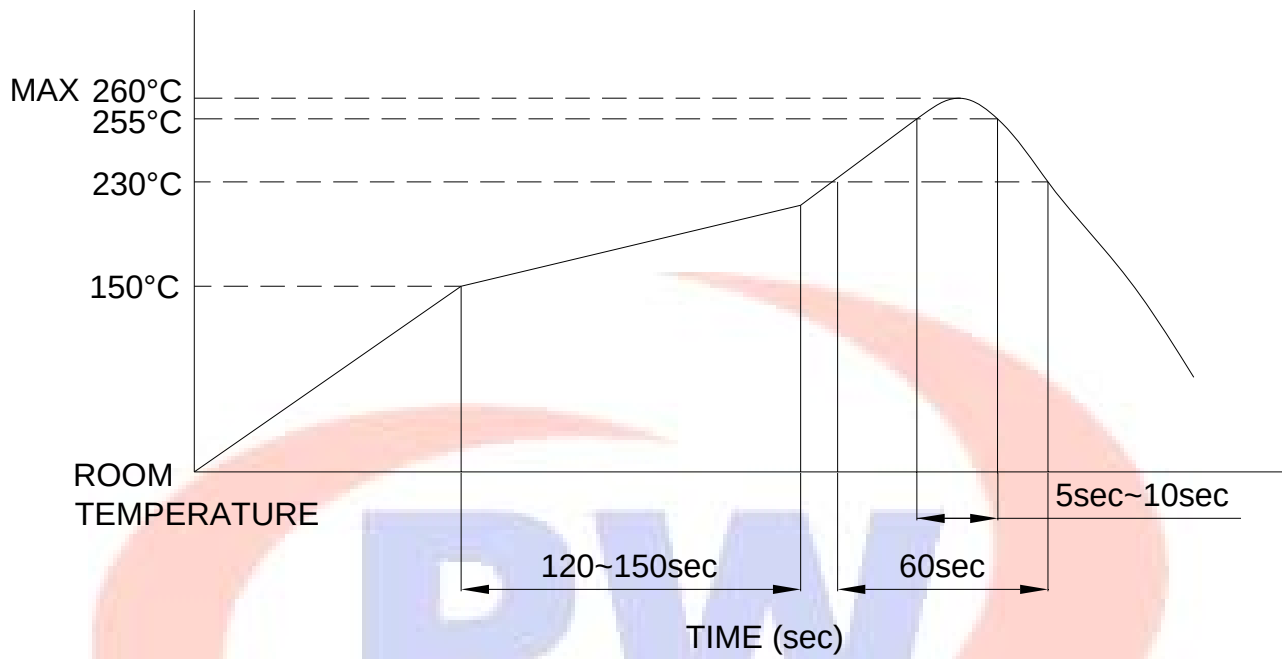
Item		Test conditions	Performance
4.1	Durability	EIA-364-09C. 500cycles operating at a rate of 200±50 cycles per hour , without load.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
4.2	Mating Force	EIA-364-13B. Mating at the rate of 12.5mm per minute.	5.0kgf (Max.)
4.3	Unmating Force	EIA-364-13B. Mating at the rate of 12.5mm per minute.	1.4kgf(10 cycles)

*5. Environmental Performance:*

Item		Test conditions	Performance
5.1	Heat Test	EIA-364-17B. 70°C±2°C for 96 hours. After test kept under 25 °C & 40%-60%RH for 30 minutes.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
5.2	Humidity Test	EIA-364-31B. 40°C±2°C, 90-95% RH for 96 hours. After test kept under 25 °C & 40%-60%RH for 30 minutes.	(1) Contact Resistance:100mΩ Max (2) There shall be no functional defects.
5.3	Soldering Heat Resistance Test	EIA-364-56C. Equipment conditions refer to the following recommended reflow soldering profile.	(1) Contact Resistance:100mΩ Max (2) Mechanical and electrical characteristics shall be satisfied.
5.4	Solderability Test	EIA-364-52B. The top of the terminals shall be dipped 2mm in the solder bath of 245°C±5°C for 5±1.0 seconds.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.



REFLOW SOLDERING PROFILE



RECOMMENDED REFLOW SOLDERING CURVE

*6. Test Group and Sequence:*

ITEM	DESCRIPTION	TEST GROUP				
		A	B	C	D	E
		TEST SEQUENCE				
1	Visual inspection	1	1	1	1	1,3
2	Contact Resistance	2,7	2,4	2,4	2,4	
3	Insulation Resistance	3,8				
4	Withstanding Voltage	4,9				
5	Mating & Unmating Force	5,10				
6	Durability	6				
7	Heat Test		3			
8	Humidity Test			3		
9	Soldering Heat Resistance Test				3	
10	Solderability Test					2
Sample Size(pcs)		5	5	5	5	5

Note: